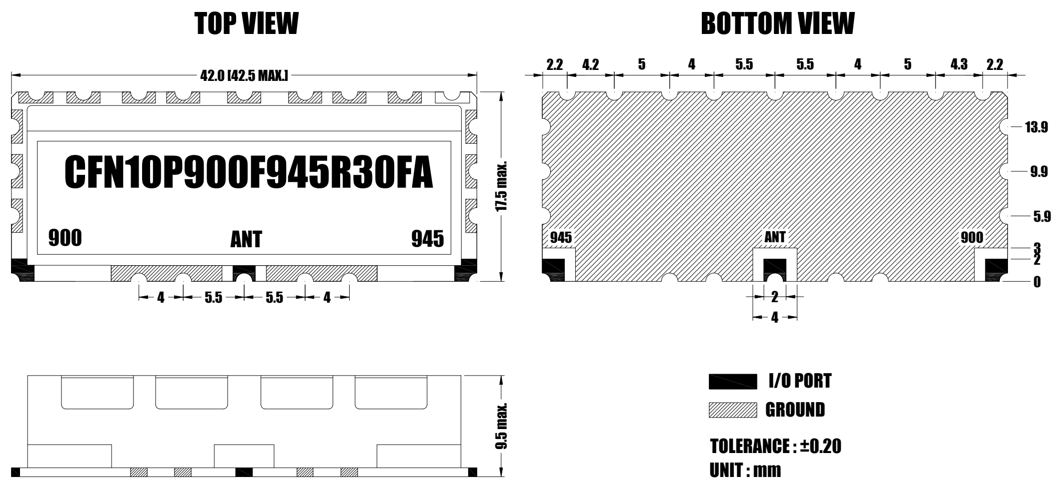
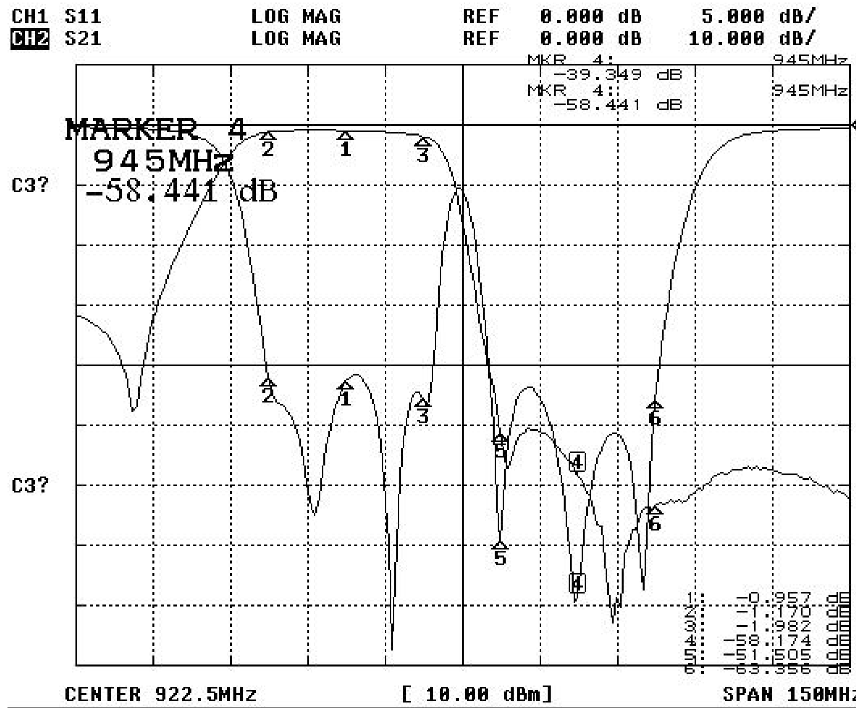
Electrical Specification

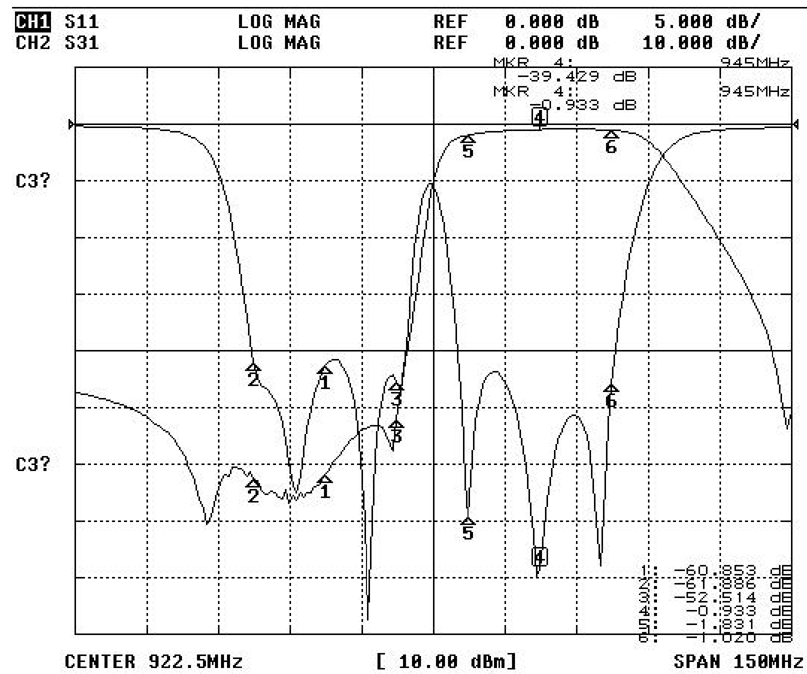
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	900.0	945.0	MHz
Bandwidth [BW]	fo ±15.0[885.0 ~915.0]	fo ±15.0[930.0 ~960.0]	MHz
Insertion Loss in BW	2.5	2.5	dB max
Ripple in BW	1.5	1.5	dB max
Return Loss in BW	15.0	15.0	dB min
Attenuation	45.0 dB min. @[930 ~960]	45.0 dB min. @[885 ~915]	MHz
☑ Absolute Value	dB min. @ [~]	dB min. @ [~]	MHz
☐ Relative Value	dB min. @ [~]	dB min. @ [~]	MHz
	dB min. @ [~]	dB min. @ [~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40℃ to +85℃		

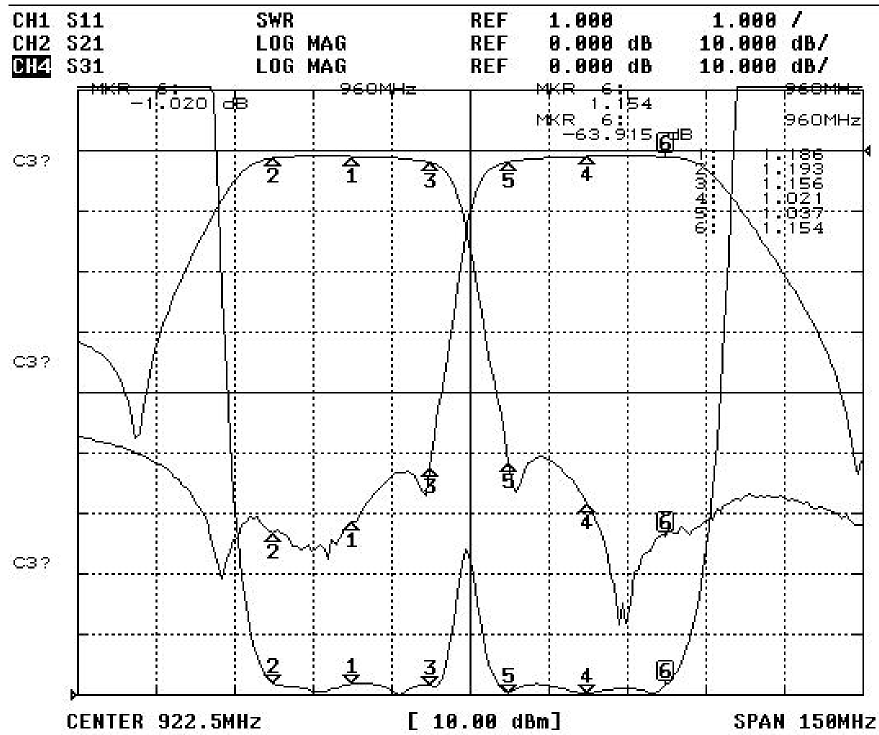
Mechanical Specification

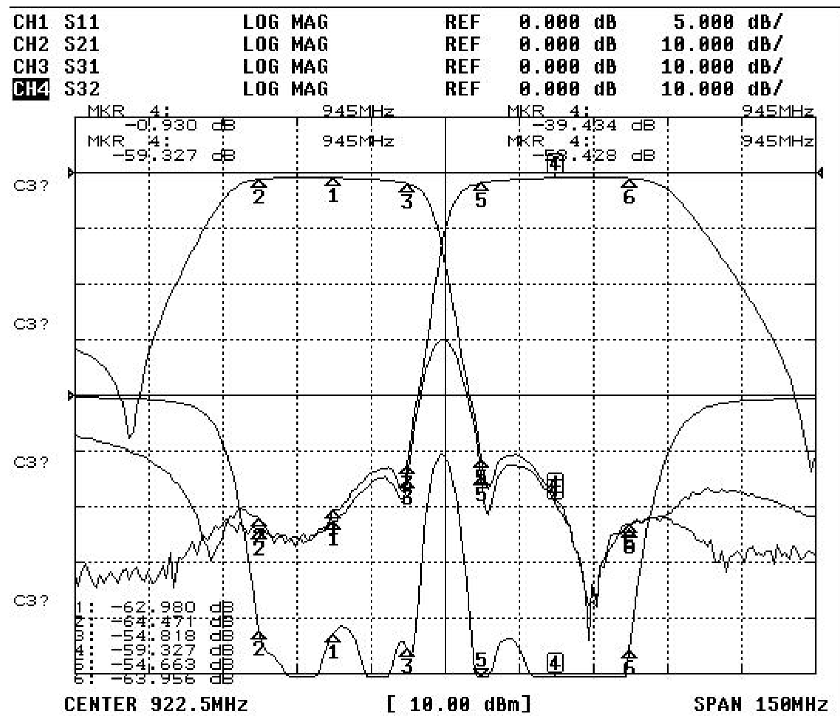


Plot Data

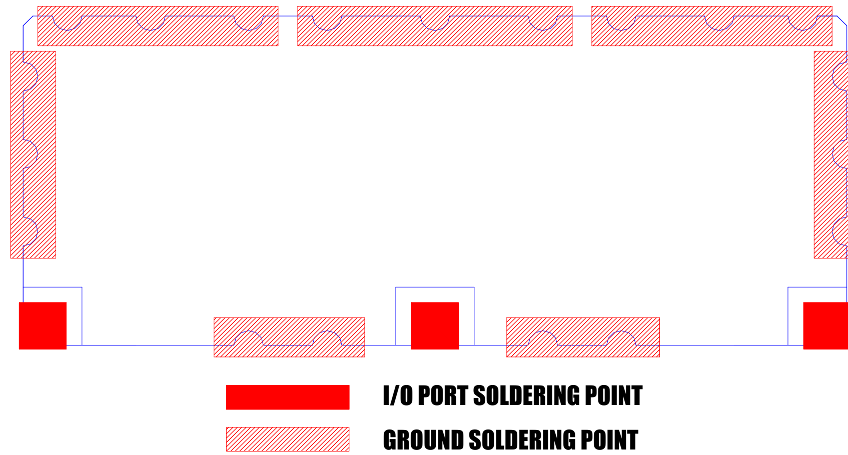




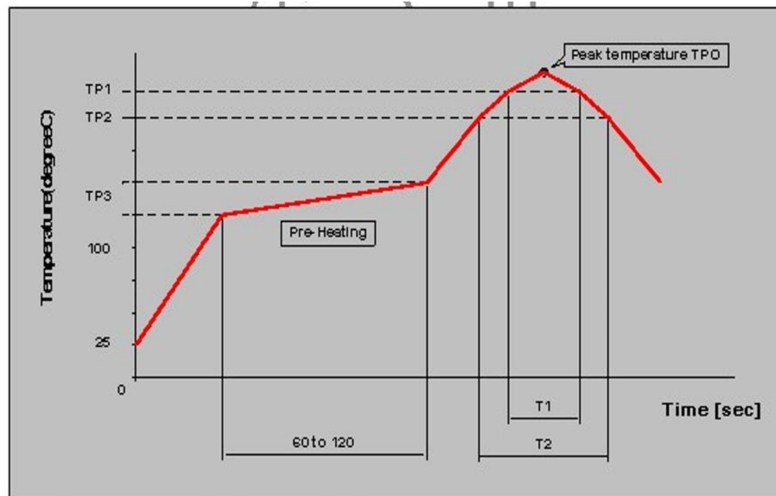

CH1 S11 SWR REF 1.000 1.000 /
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S31 LOG MAG REF 0.000 dB 10.000 dB/
MKR 6: -1.020 dB 960MHz
MKR 6: 1.154 960MHz
MKR 6: -63.915 dB 960MHz
1: 1.186
2: 1.193
3: 1.156
4: 1.021
5: 1.037
6: 1.154
CENTER 922.5MHz
[10.00 dBm]
SPAN 150MHz


CH1 S11 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH3 S31 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S32 LOG MAG REF 0.000 dB 10.000 dB/
MKR 4: -0.930 dB 945MHz
MKR 4: -59.327 dB 945MHz
MKR 4: -39.434 dB 945MHz
MKR 4: -59.428 dB 945MHz
1: -62.980 dB
2: -64.471 dB
3: -54.818 dB
4: -59.327 dB
5: -54.663 dB
6: -63.956 dB
CENTER 922.5MHz
[10.00 dBm]
SPAN 150MHz

Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180